

## 2SK2949-VB Datasheet

## N-Channel 550V (D-S) Power MOSFET

## PRODUCT SUMMARY

|                                    |                        |      |
|------------------------------------|------------------------|------|
| $V_{DS}$ (V)                       | 550                    |      |
| $R_{DS(on)}$ at 25 °C ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ | 0.26 |
| $Q_g$ max. (nC)                    | 150                    |      |
| $Q_{gs}$ (nC)                      | 12                     |      |
| $Q_{gd}$ (nC)                      | 25                     |      |
| Configuration                      | Single                 |      |

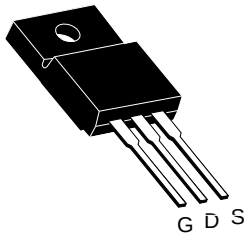
## FEATURES

- Optimal Design
  - Low Area Specific On-Resistance
  - Low Input Capacitance ( $C_{iss}$ )
  - Reduced Capacitive Switching Losses
  - High Body Diode Ruggedness
  - Avalanche Energy Rated (UIS)
- Optimal Efficiency and Operation
  - Low Cost
  - Simple Gate Drive Circuitry
  - Low Figure-of-Merit (FOM):  $R_{on} \times Q_g$
  - Fast Switching

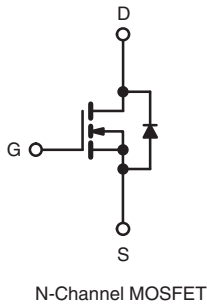


**RoHS\***  
 COMPLIANT  
 HALOGEN  
**FREE**  
 Available

TO-220 FULLPAK



Top View



N-Channel MOSFET

## APPLICATIONS

- Consumer Electronics
  - Displays (LCD or Plasma TV)
- Server and Telecom Power Supplies
  - SMPS
- Industrial
  - Welding
  - Induction Heating
  - Motor Drives
- Battery Chargers
- SMPS
  - Power Factor Correction (PFC)

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ °C}$ , unless otherwise noted)

| PARAMETER                                          | SYMBOL           | LIMIT                 | UNIT |
|----------------------------------------------------|------------------|-----------------------|------|
| Drain-Source Voltage                               | $V_{DS}$         | 550                   | V    |
| Gate-Source Voltage                                | $V_{GS}$         | $\pm 20$              |      |
| Gate-Source Voltage AC ( $f > 1\text{ Hz}$ )       |                  | 30                    |      |
| Continuous Drain Current ( $T_J = 150\text{ °C}$ ) | $V_{GS}$ at 10 V | $T_C = 25\text{ °C}$  | A    |
|                                                    |                  | $T_C = 100\text{ °C}$ |      |
| Pulsed Drain Current <sup>a</sup>                  | $I_{DM}$         | 56                    |      |
| Linear Derating Factor                             |                  | 2.2                   | W/°C |
| Single Pulse Avalanche Energy <sup>b</sup>         | $E_{AS}$         | 281                   | mJ   |
| Maximum Power Dissipation                          | $P_D$            | 60                    | W    |
| Operating Junction and Storage Temperature Range   | $T_J, T_{stg}$   | - 55 to + 150         | °C   |
| Drain-Source Voltage Slope                         | $dV/dt$          | $T_J = 125\text{ °C}$ | V/ns |
| Reverse Diode $dV/dt$ <sup>d</sup>                 |                  | 0.36                  |      |
| Soldering Recommendations (Peak Temperature)       |                  | for 10 s              | 300° |

## Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ °C}$ ,  $L = 10\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 7.5\text{ A}$ .
- 1.6 mm from case.
- $I_{SD} \leq I_D$ , starting  $T_J = 25\text{ °C}$ .

**THERMAL RESISTANCE RATINGS**

| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum Junction-to-Ambient      | $R_{thJA}$ | -    | 40   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$ | -    | 0.45 |      |

**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

| PARAMETER                                                 | SYMBOL              | TEST CONDITIONS                                                                                                                                          |                                               | MIN. | TYP. | MAX.      | UNIT                 |
|-----------------------------------------------------------|---------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|------|------|-----------|----------------------|
| Static                                                    |                     |                                                                                                                                                          |                                               |      |      |           |                      |
| Drain-Source Breakdown Voltage                            | $V_{DS}$            | $V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$                                                                                                   |                                               | 550  | -    | -         | V                    |
| $V_{DS}$ Temperature Coefficient                          | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^{\circ}\text{C}$ , $I_D = 250\text{ }\mu\text{A}$                                                                               |                                               | -    | 0.56 | -         | $V/^{\circ}\text{C}$ |
| Gate-Source Threshold Voltage (N)                         | $V_{GS(th)}$        | $V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$                                                                                                       |                                               | 2    | -    | 4         | V                    |
| Gate-Source Leakage                                       | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$                                                                                                                               |                                               | -    | -    | $\pm 100$ | nA                   |
| Zero Gate Voltage Drain Current                           | $I_{DSS}$           | $V_{DS} = 500\text{ V}$ , $V_{GS} = 0\text{ V}$                                                                                                          |                                               | -    | -    | 1         | $\mu\text{A}$        |
|                                                           |                     | $V_{DS} = 400\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 125\text{ }^{\circ}\text{C}$                                                                    |                                               | -    | -    | 10        |                      |
| Drain-Source On-State Resistance                          | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}$                                                                                                                                   | $I_D = 10\text{ A}$                           | -    | 0.26 | -         | $\Omega$             |
| Forward Transconductance                                  | $g_{fs}$            | $V_{DS} = 50\text{ V}$ , $I_D = 10\text{ A}$                                                                                                             |                                               | -    | 12   | -         | S                    |
| Dynamic                                                   |                     |                                                                                                                                                          |                                               |      |      |           |                      |
| Input Capacitance                                         | $C_{iss}$           | $V_{GS} = 0\text{ V}$ ,<br>$V_{DS} = 100\text{ V}$ ,<br>$f = 1\text{ MHz}$                                                                               |                                               | -    | 3094 | -         | pF                   |
| Output Capacitance                                        | $C_{oss}$           |                                                                                                                                                          |                                               | -    | 152  | -         |                      |
| Reverse Transfer Capacitance                              | $C_{rss}$           |                                                                                                                                                          |                                               | -    | 13   | -         |                      |
| Effective output capacitance, energy related <sup>a</sup> | $C_{o(er)}$         | $V_{GS} = 0\text{ V}$ ,<br>$V_{DS} = 0\text{ V to } 400\text{ V}$                                                                                        |                                               | -    | 131  | -         |                      |
| Effective output capacitance, time related <sup>b</sup>   | $C_{o(tr)}$         |                                                                                                                                                          |                                               | -    | 189  | -         |                      |
| Total Gate Charge                                         | $Q_g$               | $V_{GS} = 10\text{ V}$                                                                                                                                   | $I_D = 10\text{ A}$ , $V_{DS} = 400\text{ V}$ | -    | 80   | 150       | nC                   |
| Gate-Source Charge                                        | $Q_{gs}$            |                                                                                                                                                          |                                               | -    | 12   | -         |                      |
| Gate-Drain Charge                                         | $Q_{gd}$            |                                                                                                                                                          |                                               | -    | 25   | -         |                      |
| Turn-On Delay Time                                        | $t_{d(on)}$         | $V_{DD} = 400\text{ V}$ , $I_D = 10\text{ A}$ ,<br>$V_{GS} = 10\text{ V}$ , $R_g = 9.1\text{ }\Omega$                                                    |                                               | -    | 24   | 50        | ns                   |
| Rise Time                                                 | $t_r$               |                                                                                                                                                          |                                               | -    | 31   | 62        |                      |
| Turn-Off Delay Time                                       | $t_{d(off)}$        |                                                                                                                                                          |                                               | -    | 117  | 176       |                      |
| Fall Time                                                 | $t_f$               |                                                                                                                                                          |                                               | -    | 56   | 112       |                      |
| Gate Input Resistance                                     | $R_g$               | $f = 1\text{ MHz}$ , open drain                                                                                                                          |                                               | -    | 1.8  | -         | $\Omega$             |
| Drain-Source Body Diode Characteristics                   |                     |                                                                                                                                                          |                                               |      |      |           |                      |
| Continuous Source-Drain Diode Current                     | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode<br> |                                               | -    | -    | 20        | A                    |
| Pulsed Diode Forward Current                              | $I_{SM}$            |                                                                                                                                                          |                                               | -    | -    | 80        |                      |
| Diode Forward Voltage                                     | $V_{SD}$            | $T_J = 25\text{ }^{\circ}\text{C}$ , $I_S = 10\text{ A}$ , $V_{GS} = 0\text{ V}$                                                                         |                                               | -    | -    | 1.2       | V                    |
| Reverse Recovery Time                                     | $t_{rr}$            | $T_J = 25\text{ }^{\circ}\text{C}$ , $I_F = I_S = 10\text{ A}$ ,<br>$di/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 20\text{ V}$                             |                                               | -    | 437  | -         | ns                   |
| Reverse Recovery Charge                                   | $Q_{rr}$            |                                                                                                                                                          |                                               | -    | 5.9  | -         | $\mu\text{C}$        |
| Reverse Recovery Current                                  | $I_{RRM}$           |                                                                                                                                                          |                                               | -    | 25   | -         | A                    |

**Notes**

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .  
 b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

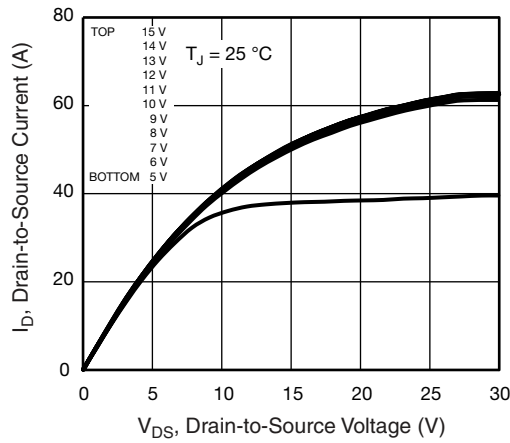


**Fig. 1 - Typical Output Characteristics**

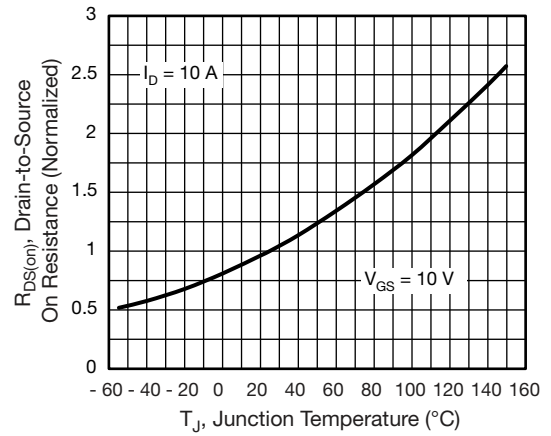


**Fig. 4 - Normalized On-Resistance vs. Temperature**

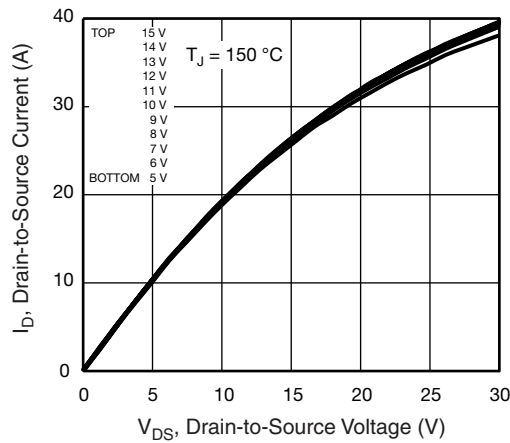


**Fig. 2 - Typical Output Characteristics**

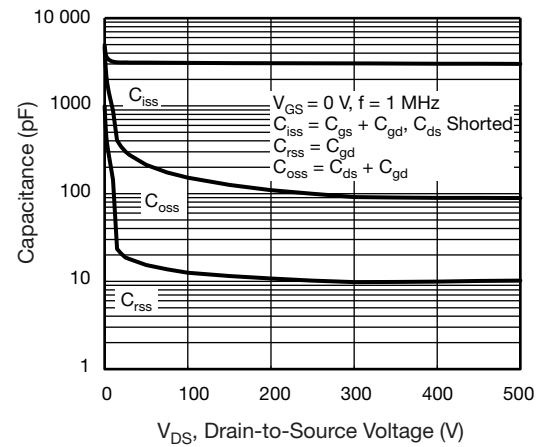


**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

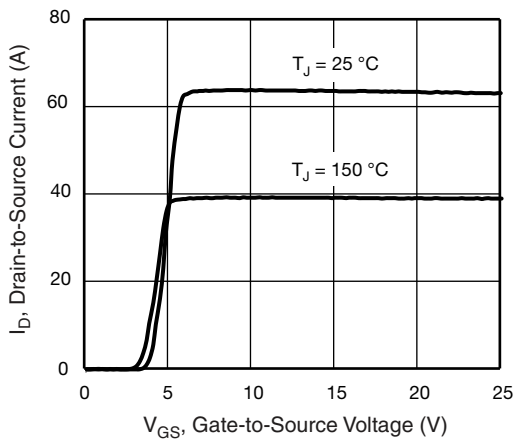


**Fig. 3 - Typical Transfer Characteristics**

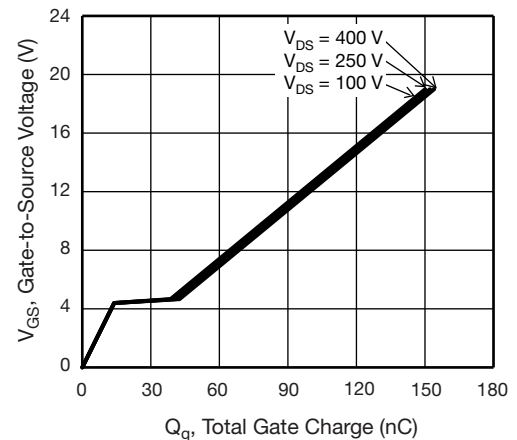


**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**

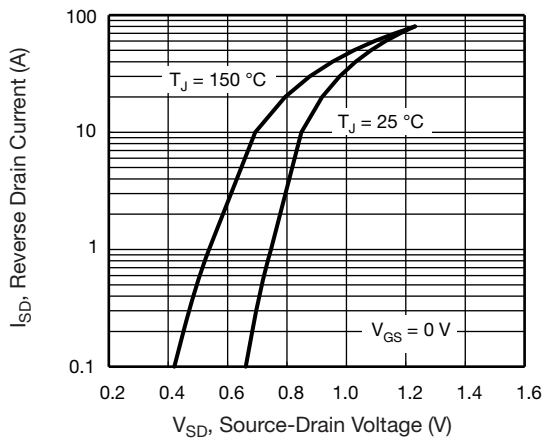


Fig. 7 - Typical Source-Drain Diode Forward Voltage

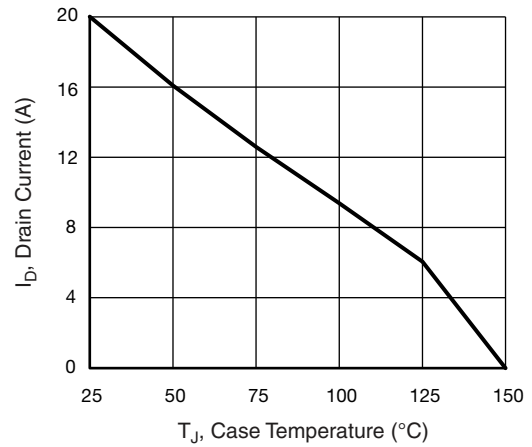


Fig. 9 - Maximum Drain Current vs. Case Temperature

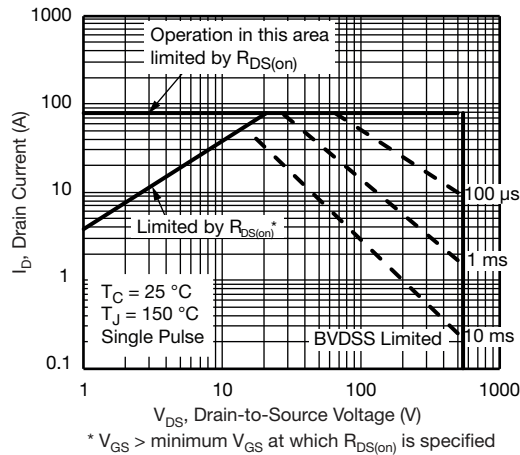


Fig. 8 - Maximum Safe Operating Area

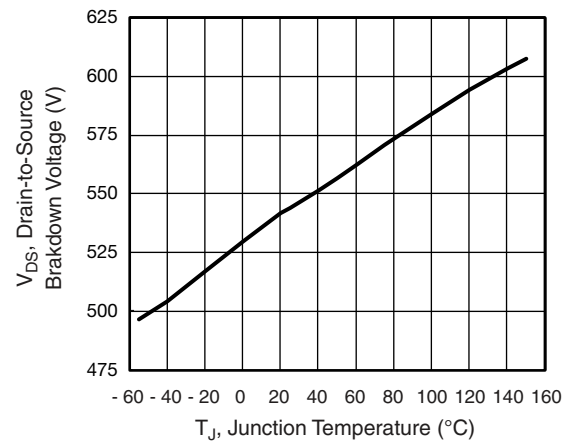


Fig. 10 - Temperature vs. Drain-to-Source Voltage

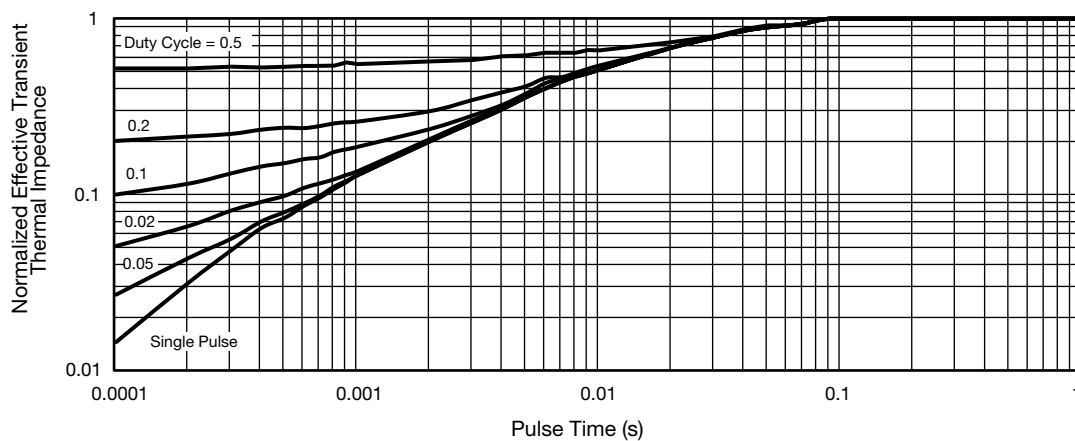


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

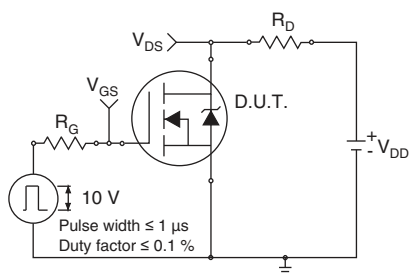


**Fig. 12 - Switching Time Test Circuit**

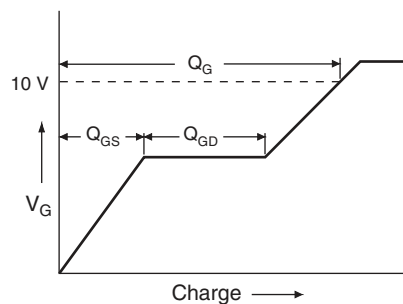


**Fig. 16 - Basic Gate Charge Waveform**

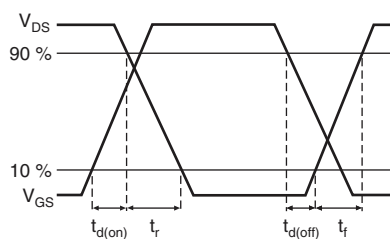


**Fig. 13 - Switching Time Waveforms**

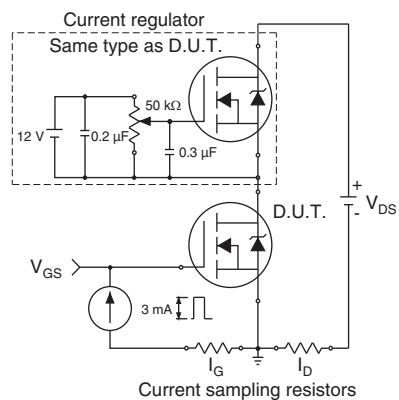


**Fig. 17 - Gate Charge Test Circuit**

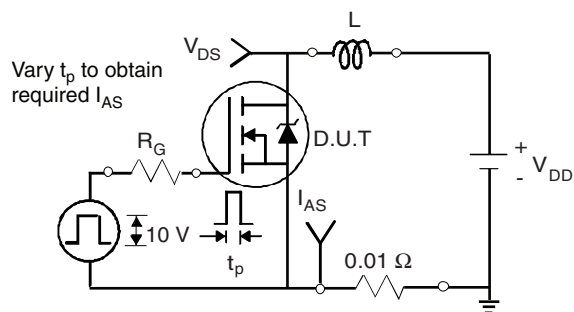


**Fig. 14 - Unclamped Inductive Test Circuit**

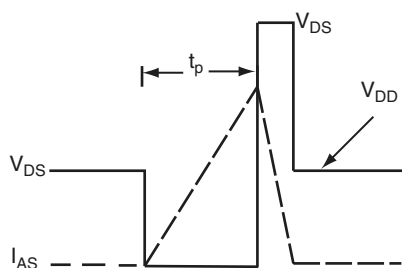
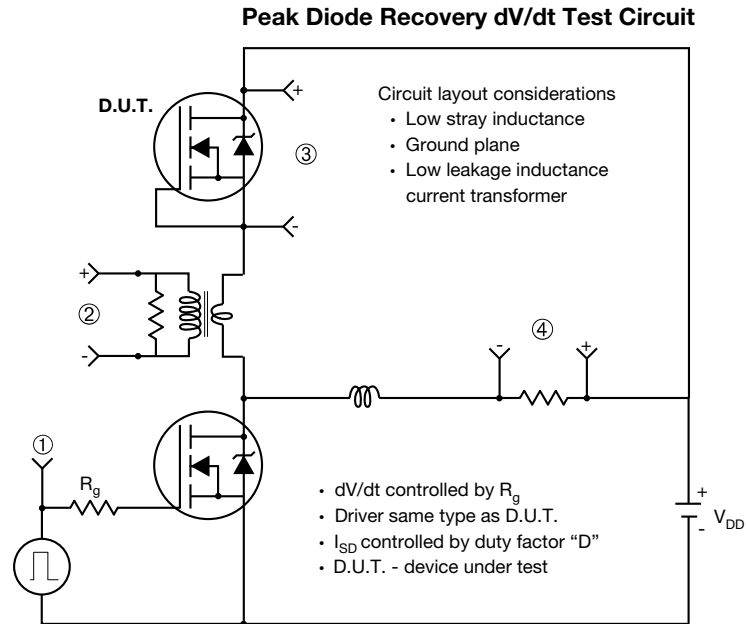
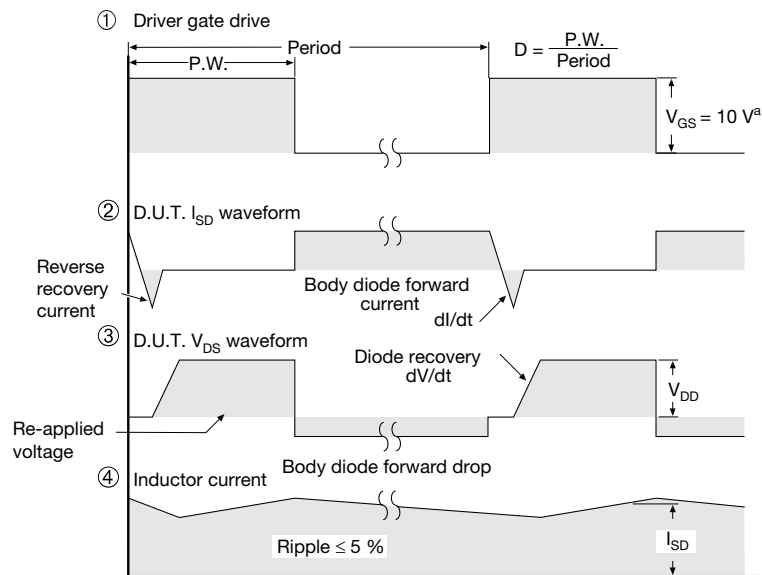
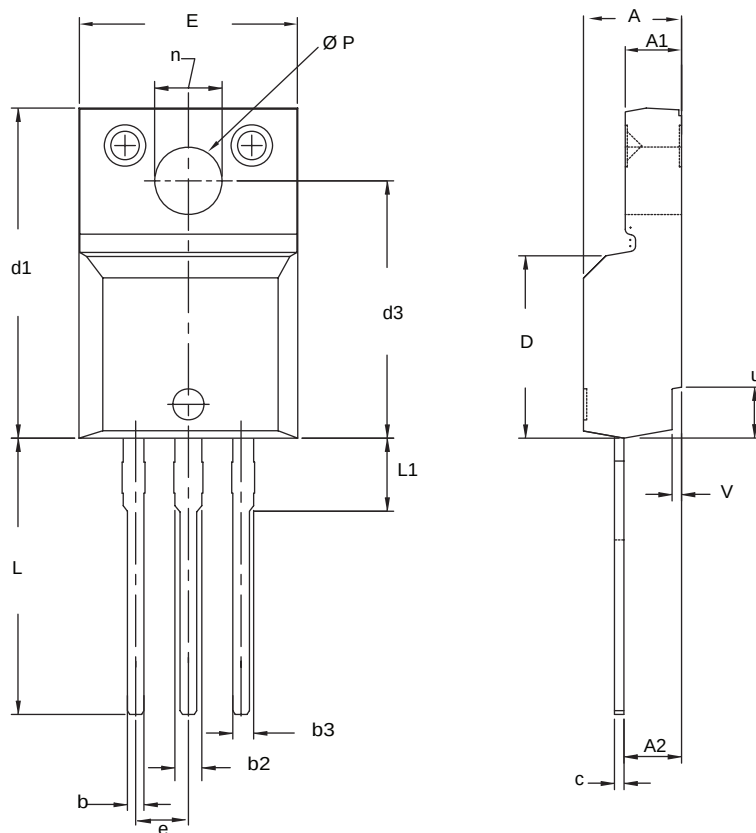


**Fig. 15 - Unclamped Inductive Waveforms**

**Note**a.  $V_{GS} = 5 V$  for logic level devices**Fig. 18 - For N-Channel**

**TO-220 FULLPAK (HIGH VOLTAGE)**

| DIM. | MILLIMETERS |        | INCHES    |       |
|------|-------------|--------|-----------|-------|
|      | MIN.        | MAX.   | MIN.      | MAX.  |
| A    | 4.570       | 4.830  | 0.180     | 0.190 |
| A1   | 2.570       | 2.830  | 0.101     | 0.111 |
| A2   | 2.510       | 2.850  | 0.099     | 0.112 |
| b    | 0.622       | 0.890  | 0.024     | 0.035 |
| b2   | 1.229       | 1.400  | 0.048     | 0.055 |
| b3   | 1.229       | 1.400  | 0.048     | 0.055 |
| c    | 0.440       | 0.629  | 0.017     | 0.025 |
| D    | 8.650       | 9.800  | 0.341     | 0.386 |
| d1   | 15.88       | 16.120 | 0.622     | 0.635 |
| d3   | 12.300      | 12.920 | 0.484     | 0.509 |
| E    | 10.360      | 10.630 | 0.408     | 0.419 |
| e    | 2.54 BSC    |        | 0.100 BSC |       |
| L    | 13.200      | 13.730 | 0.520     | 0.541 |
| L1   | 3.100       | 3.500  | 0.122     | 0.138 |
| n    | 6.050       | 6.150  | 0.238     | 0.242 |
| Ø P  | 3.050       | 3.450  | 0.120     | 0.136 |
| u    | 2.400       | 2.500  | 0.094     | 0.098 |
| v    | 0.400       | 0.500  | 0.016     | 0.020 |

ECN: X09-0126-Rev. B, 26-Oct-09  
 DWG: 5972

**Notes**

1. To be used only for process drawing.
2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
3. All critical dimensions should C meet  $C_{pk} > 1.33$ .
4. All dimensions include burrs and plating thickness.
5. No chipping or package damage.

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